EFS-Web Receipt date: 08/14/2006

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SHEET 1 OF 1

Form PTO 1449	U.S. DEPARTMENT OF COMMERCE			ATTY DOCKET NO.		SERIAL NO.		
(Modified)		PATENT AND TRAD	EMARK OFFICE	291619US0PCT		10/581,111		
				APPLICANT				
LIST OF	REFE	RENCES CITED BY APP	PLICANT	Hubert MORICEAU, et al.				
				FILING DATE		GROUP		
				May 31, 2006				
U.S. PATENT DOCUMENTS								
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE	
/S.J.N./	AA ·	~ 2003/211703	11/13/03	TONG, Qin-Yi et al.				
/S.J.N./	AB	4 983 251	01/08/91	HAISMA, Jan et al.				
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FOREIGN PATENT DOCUMENTS								
		DOCUMENT	DATE	COUNTRY	COUNTRY		TRANSLATION	
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/S.J.N./	AO	2 787 919	06/30/00	FR(with English abstract)			NO	
/S.J.N./	AP	2 796 491	01/19/01	FR(equivalent of US 6 821 376)			NO	
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OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)								
	TONG O.Y. et al. "Semiconductor Wafer Bonding, Science and Technology". The Electrochemical Society Series, Wiley-							
/S.J.N./	AW	Interscience, John Wiley and Sons, Inc., New York (1999).						
/S.J.N./	AX	MORICEAU, H. et al., "The Bonding Energy Control: An Original Way To Debondable Substrates", Conference of International Electrochemical Society, Paris, June 2003.						
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Examiner	/Seat	vosh Nikmanesh/			Date Considered 02/13/2008			
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								